

The drawings are objected to as failing to comply with 37 CFR § 1.84(p)(4) and § 1.84(p)(5).

The disclosure is objected to for various informalities.

The claims are objected to as failing to comply with 37 CFR § 1.126.

Claims 10 and 24 are rejected under 37 CFR § 112, second paragraph.

Claim 23 is rejected under 37 CFR § 112, second paragraph.

Claims 1 - 4, 10, and 13 - 16 are rejected under 35 USC § 102(e) as being anticipated by U.S. Patent No. 5,891,807, to Muller et al.

Claims 5 - 9, 11, and 12 are objected to as being dependent upon a rejected base claim, but are indicated to be allowable if rewritten in independent form, including all of the limitations of the base claim and any intervening claims.

Claims 23 and 24 are said to be allowable if rewritten so as to overcome their respective rejections under 35 USC § 112, second paragraph, and also to include all of the limitations of the base claim and any intervening claims.

Please amend the application as follows.

IN THE SPECIFICATION:

Please replace the paragraph at page 5, lines 6 - 8, with the following rewritten paragraph:

A1
-- Figure 1C shows the structure of Figure 1B after the protective layer has been anisotropically etched to remove a portion of the protective layer which overlies the bottom 110 of shaped opening 104. --

Please replace the paragraph at page 5, lines 9 - 13, with the following rewritten paragraph:

A2
-- Figure 1D shows the structure of Figure 1C after the underlying substrate 102 has been etched using the multi-step etch method of the invention to form a shaped cavity 112 which underlies shaped opening 104. The shaped cavity 112 is etched to have a width B and a depth C, where the

A2
Contd.

width B is equal to or greater than the depth C. In particular, here, width B is equal to depth C, so that the shaped cavity 112 is formed in a round, as shown. --

✓ ✓ ✓
Please replace the paragraph at page 15, lines 18 - 20, with the following rewritten paragraph:

A3

-- Referring to Figure 1C, the protective layer 106 may be anisotropically etched to remove portions of the protective layer which overlie the bottom 110 of the shaped opening 104. Anisotropic etching is performed using apparatus and techniques known in the art. --

✓ ✓ ✓
Please replace the paragraph at page 19, lines 4 - 12, with the following rewritten paragraph:

A4

-- Figure 1D shows the structure of Figure 1C after etching of shaped cavity 112 using the method of the invention. The shaped cavity 112 is etched to have a width B and a depth C, where the width B is equal to or greater than the depth C. As shown in Figure 1D, the shaped cavity 112 directly underlies and is in continuous communication with the shaped opening 104. The protective layer 106 effectively preserves the profile of the shaped opening 104 during etching of the underlying shaped cavity 112 using the method of the invention. The shaped cavity 112 shown in Figure 1D has been etched so that the width B is approximately equal to the depth C, resulting in the formation of a substantially round shaped cavity. --

✓ ✓ ✓ ✓
Please replace the paragraph at page 21, line 20, through page 22, line 6, with the following rewritten paragraph:

A5

-- Preferably, the apparatus used to practice the present invention is adapted to be controlled by a computer. Figure 4 shows a computer 400. Computer 400 comprises a processor 402, memory 404 adapted to store instructions 406, and one or more ports 408. Processor 402 is adapted to communicate with memory 404 and to execute instructions 406. Processor 402 and memory 404 are also adapted to communicate with one or more ports 408. Ports 408 are adapted to communicate